OKI Semiconductor

Previous version: Nov. 1996

MSM7543/7544

Single Rail CODEC

GENERAL DESCRIPTION

The MSM7543 and MSM7544 are single-channel CODEC CMOS ICs for voice signals ranging from 300 to 3400 Hz. These devices contain filters for A/D and D/A conversion.

Designed especially for a single-power supply and low-power applications, these devices are optimized for telephone terminals in digital wireless systems, ISDN terminals, and digital PBXs. The MSM7543 and MSM7544 use newly-designed operational amplifiers to keep small current deviations caused by power voltage fluctuations.

The devices use the same transmission clocks as those used in the MSM7508B and MSM7509B. The analog output signal, which is of a differential type and can drive a 600 Ω load, can directly drive a handset receiver.

FEATURES

• Single power supply: +5 V ±5%

Low power consumption

31.5 mW Max. 20 mW Typ. $V_{DD} = 5 V$ Operating mode: 4.5 mW Typ. $V_{DD} = 5 V$ Power save mode: 8 mW Max. Power down mode: 1.5 mW Typ. 3 mW Max. $V_{DD} = 5 V$

ITU-T Companding law

MSM7543: μ-law MSM7544: A-law

- The transmission characteristics of the devices comply with ITU-T G.714
- Built-in PLL eliminates a master clock
- Serial data rate: 64/128/256/512/1024/2048 kHz 96/192/384/768/1536/1544 kHz
- Adjustable transmit gain
- Adjustable receive gain
- Built-in reference voltage supply
- Built-in analog loop back test mode
- Differential type analog output. Directly drives a 600 Ω line transformer
- Package options:

20-pin plastic skinny DIP (DIP20-P-300-2.54-S1) (Product name: MSM7543RS) (Product name : MSM7544RS)

24-pin plastic SOP (SOP24-P-430-1.27-K) (Product name: MSM7543GS-K)

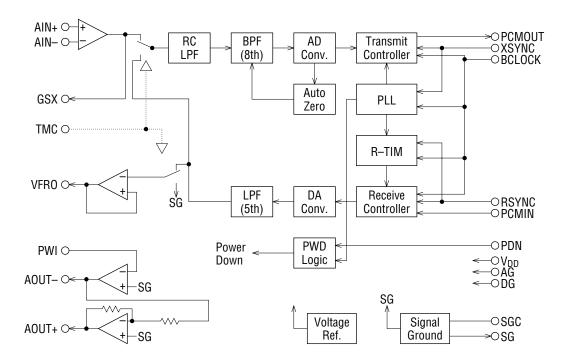
(Product name: MSM7544GS-K)

This version: Aug. 1998

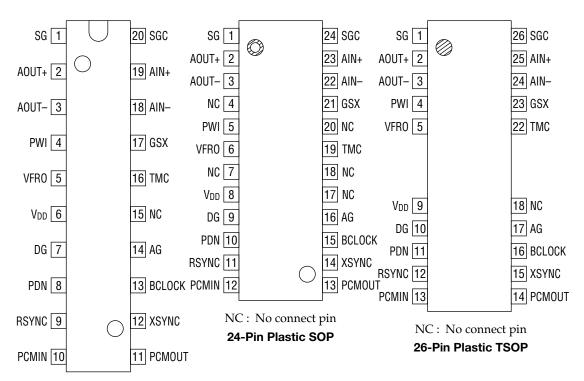
26-pin plastic TSOP (TSOPII26/20-P-300-1.27-K) (Product name: MSM7543TS-K)

(Product name: MSM7544TS-K)

BLOCK DIAGRAM



PIN CONFIGURATION (TOP VIEW)



NC : No connect pin **20-Pin Plastic Skinny DIP**

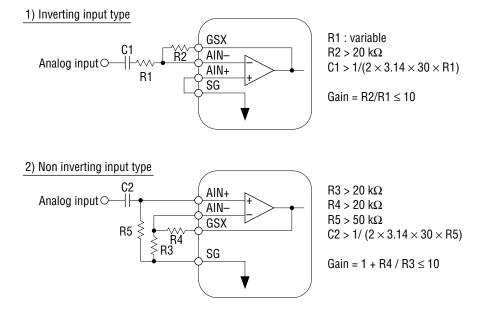
PIN AND FUNCTIONAL DESCRIPTIONS

AIN+, AIN-, GSX

Transmit analog input and transmit level adjustment.

AIN+ is a non-inverting input to the op-amp; AIN- is an inverting input to the op-amp; GSX is connected to the output of the op-amp and is used to adjust the level, as shown below. When not using AIN- and AIN+, connect AIN- to GSX and AIN+ to SG. During power saving

When not using AIN– and AIN+, connect AIN– to GSX and AIN+ to SG. During power savir and power down modes, the GSX output is at AG voltage.



AG

Analog signal ground.

VFRO

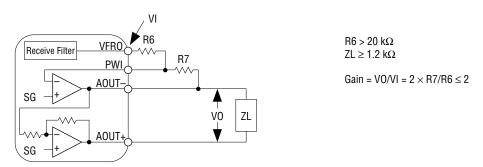
Receive filter output.

The output signal has an amplitude of 2.4 V_{PP} above and below the signal ground voltage (SG) when the digital signal of +3 dBmO is input to PCMIN and can drive a load of 20 k Ω or more. For driving a load of 20 k Ω or less, connect a resistor of 20 k Ω or more between the pins VFRO and PWI.

When adding the frequency characteristics to the receive signal, refer to the application example. During power saving or power down mode, the output of VFRO is at the voltage level of AG.

PWI, AOUT+, AOUT-

PWI is connected to the inverting input of the receive driver. The receive driver output is connected to the AOUT– pin. Therefour, the receive level can be adjusted with the pins VFRO, PWI, and AOUT–. When the PWI pin is not used, connect the PWI pin to the AOUT– pin, and leave open the pins AOUT– and AOUT+. The output of AOUT+ is inverted with respect to the output of AOUT–. Since the signal from which provides differential drive of an impedance of 1.2 $k\Omega$, these outputs can directly be connected to a receiver of handset using a piezoelectric earphone. Refer to the application example.



During power saving and power down modes, the outputs of AOUT+ and AOUT- are in a high impedance state .

The electrical driving capability of the AOUT– pin and AOUT+ pin is ± 1.3 V maximum. The output load resistor has a minimum value of 0.6 k Ω .

If an output amplitude less than ± 1.3 V is allowed, these outputs can drive a load resistance less than that described above.

For more details, refer to SINGLE POWER SUPPLY PCM CODEC APPLICATION NOTE.

V_{DD}

Power supply pin for +5 V.

PCMIN

PCM signal input.

A serial PCM signal input to this pin is converted to an analog signal in synchronization with the RSYNC signal and BCLOCK signal.

The data rate of the PCM signal is equal to the frequency of the BCLOCK signal.

The PCM signal is shifted at a falling edge of the BCLOCK signal and latched into the internal register when shifted by eight bits.

The start of the PCM data (MSD) is identified at the rising edge of RSYNC.

BCLOCK

Shift clock signal input for the PCMIN and PCMOUT signal.

The frequency, equal to the data rate, is 64, 96, 128, 192, 256, 384, 512, 768, 1024, 1536, 1544, 2048, or 200 kHz. Setting this signal to logic "1" or "0" drives both transmit and receive circuits to the power saving state.

RSYNC

Receive synchronizing signal input.

Eight required bits are selected from serial PCM signals on the PCMIN pin by the receive synchronizing signal.

Signals in the receive section are synchronized by this synchronizing signal. This signal must be synchronized in phase with the BCLOCK. The frequency should be $8\,\mathrm{kHz}\pm50\,\mathrm{ppm}$ to guarantee the AC characteristics which are mainly the frequency characteristics of the receive section. However, if the frequency characteristic of an applied system is not specified exactly, this device can operate in the range of $8\,\mathrm{kHz}\pm2\,\mathrm{kHz}$, but the electrical characteristics in this specification are

not guaranteed.

XSYNC

Transmit synchronizing signal input.

The PCM output signal from the PCMOUT pin is output in synchronization with this transmit synchronizing signal. This synchronizing signal triggers the PLL and synchronizes all timing signals of the transmit section.

This synchronizing signal must be synchronized in phase with BCLOCK.

The frequency should be $8 \text{ kHz} \pm 50 \text{ ppm}$ to guarantee the AC characteristics which are mainly the frequency characteristics of the transmit section.

However, if the frequency characteristic of an applied system is not specified exactly, this device can operate in the range of $8\,\mathrm{kHz}\pm2\,\mathrm{kHz}$, but the electrical characteristics in this specification are not guaranteed.

Setting this signal to logic "1" or "0" drives both transmit and receive circuits to the power saving state.

TMC

Control signal input for mode selection.

This pin select the normal operating mode or the analog loop-back mode.

In the analog loop-back mode, the receive filter output is connected to the transmit filter input and the digital signal input to the PCMIN pin is converted from a digital to an analog signal (D/A conversion). Next, the analog signal is converted to a digital signal (A/D conversion) through the receive filter and transmit filter. The result is output to the PCMOUT pin.

When in the analog loop-back mode, the VFRO pin outputs the SG level. (signal ground)

TMC Input	Mode
< 0.8 V	Normal operation
> 2.2 V	Analog loop-back

DG

Ground for the digital signal circuits.

This ground is separate from the analog signal ground. The DG pin must be connected to the AG pin on the printed circuit board to make a common analog ground.

PDN

Power down control signal.

A logic "0" level drives both transmit and receive circuits to a power down state.

PCMOUT

PCM signal output.

The PCM output signal is output from MSD in a sequential order, synchronizing with the rising edge of the BCLOCK signal.

MSD may be output at the rising edge of the XSYNC signal, based on the timing between BCLOCK and XSYNC.

This pin is in a high impedance state except during 8-bit PCM output. It is also in a high impedance state during power saving or power down modes.

A pull-up resistor must be connected to this pin because its output is configured as an open drain. This device is compatible with the ITU-T recommendation on coding law and output coding format.

The MSM7544(A-law) outputs the character signal, inverting the even bits.

Innert (Outrout Lavel	PCMIN/PCMOUT							
Input/Output Level	MSM7543 (μ-law)	MSM7544 (A-law)						
	MSD	MSD						
+Full scale	1 0 0 0 0 0 0 0	1 0 1 0 1 0 1 0						
+0	1 1 1 1 1 1 1 1	1 1 0 1 0 1 0 1						
-0	0 1 1 1 1 1 1 1	0 1 0 1 0 1 0 1						
-Full scale	0 0 0 0 0 0 0 0	0 0 1 0 1 0 1 0						

SG

Signal ground voltage output.

The output voltage is 1/2 of the power supply voltage.

The output drive current capability is $\pm 300 \,\mu\text{A}$.

This pin provides the SG level for CODEC peripherals.

This output voltage level is undefined during power saving or power down modes.

SGC

Used to generate the signal ground voltage level by connecting a bypass capacitor.

Connect a $0.1\,\mu\text{F}$ capacitor with excellent high frequency characteristics between the AG pin and the SGC pin.

ABSOLUTE MAXIMUM RATINGS

Parameter	Symbol	Condition	Rating	Unit
Power Supply Voltage	V _{DD}	_	0 to 7	V
Analog Input Voltage	V _{AIN}	_	-0.3 to V _{DD} + 0.3	V
Digital Input Voltage	V _{DIN}	_	-0.3 to V _{DD} + 0.3	V
Storage Temperature	T _{STG}	_	−55 to +150	°C

RECOMMENDED OPERATING CONDITIONS

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Power Supply Voltage	V _{DD}	Voltage must be fixed	4.75	5.0	5.25	V
Operating Temperature	Ta	_	-30	+25	+85	°C
Analog Input Voltage	V _{AIN}	Connect AIN- and GSX		_	2.4	V _{PP}
Digital Input High Voltage	V _{IH}	XSYNC, RSYNC, BCLOCK,	2.2	_	V _{DD}	V
Digital Input Low Voltage	V _{IL}	PCMIN, PDN, TMC	0	_	0.8	V
Clock Frequency	Fc	BCLOCK	64, 128, 256, 512, 1024, 2048, 96, 192, 384, 768, 1536, 1544, 200			kHz
Sync Pulse Frequency	F _S	XSYNC, RSYNC	6.0	8.0	10.0	kHz
Clock Duty Ratio	D _C	BCLOCK	40	50	60	%
Digital Input Rise Time	t _{lr}	XSYNC, RSYNC, BCLOCK,	_	_	50	ns
Digital Input Fall Time	t _{lf}	PCMIN, PDN, TMC	_	_	50	ns
Transmit Sync Pulse Setting Time	t _{XS}	BCLOCK→XSYNC, See Timing Diagram	100	_	_	ns
Transmit Sync Fulse Setting Time	t _{SX}	$\textbf{XSYNC} {\rightarrow} \textbf{BCLOCK}, \textbf{See Timing Diagram}$	100	_		ns
Receive Sync Pulse Setting Time	t _{RS}	BCLOCK→RSYNC, See Timing Diagram	100	_	_	ns
neceive Sylic Fulse Setting Time	t _{SR}	RSYNC→BCLOCK, See Timing Diagram	100	_	_	ns
Sync Pulse Width	tws	XSYNC, RSYNC	1 BCLK	_	100	μs
PCMIN Set-up Time	t _{DS}	_	100	_	_	ns
PCMIN Hold Time	t _{DH}	_	100	_	_	ns
Digital Output Load	R _{DL}	Pull-up resistor	0.5	_	_	kΩ
Digital Output Load	C _{DL}			_	100	pF
Analog Input Allowable DC Offset	V _{off}	Transmit gain stage, Gain = 1	-100	_	+100	mV
Analog Input Allowable Do Uliset	v _{Off}	Transmit gain stage, Gain = 10	-10		+10	mV
Allowable Jitter Width	_	XSYNC, RSYNC, BCLOCK	_	_	500	ns

ELECTRICAL CHARACTERISTICS

DC and Digital Interface Characteristics

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
	I _{DD1}	Operating mode, No signal	_	4.0	6.0	mA
Power Supply Current	I _{DD2}	Power-save mode, PDN = 1, XSYNC or BCLOCK \rightarrow OFF		0.9	1.5	mA
	I _{DD3}	Power-down mode, PDN = 0	_	0.3	0.5	mA
Input High Voltage	V _{IH}	_	2.2	_	V _{DD}	V
Input Low Voltage	V _{IL}	_	0.0	_	0.8	V
High Level Input Leakage Current	I _{IH}	_	_	_	2.0	μА
Low Level Input Leakage Current	I _{IL}	_	_	_	0.5	μА
Digital Output Low Voltage	V_{OL}	Pull-up resistance $> 500 \Omega$	0.0	0.2	0.4	V
Digital Output Leakage Current	I ₀	_	_	_	10	μΑ
Input Capacitance	C _{IN}	_	_	5	_	pF

Transmit Analog Interface Characteristics

 $(V_{DD} = +5 \text{ V } \pm 5\%, \text{ Ta} = -30^{\circ}\text{C to } +85^{\circ}\text{C})$

Parameter	Symbol	Cond	Min.	Тур.	Max.	Unit	
Input Resistance	R _{INX}	AIN+, AIN-	10		_	MΩ	
Output Load Resistance	R _{LGX}	GSX with respe	20	_	_	kΩ	
Output Load Capacitance	C _{LGX}			_	_	100	pF
Output Amplitude	V _{OGX}			-1.2	_	+1.2	٧
Offset Voltage	Vosgx		Gain = 1	-20	_	+20	mV

Receive Analog Interface Characteristics

		'	00	,		,	
Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit	
Input Resistance	R _{INPW}	PWI	10	_	_	MΩ	
	R _{LVF}	VFRO with respect to SG	20	_	_	kΩ	
Output Load Resistance	В	AOUT+, AOUT- (each) with	0.6			10	
	R _{LAO}	respect to SG	0.6	_	_	kΩ	
0.1.1.10	C _{LVF}	VFR0	_	_	100	pF	
Output Load Capacitance	C _{LAO}	AOUT+, AOUT-	_	_	50	pF	
	W	VFRO, $R_L = 20 \text{ k}\Omega$ with	4.0		+1.2	W	
Outout Amenithed	V _{OVF}	respect to SG	-1.2	_		V	
Output Amplitude	V	AOUT+, AOUT-, $R_L = 1.2 \text{ k}\Omega$	4.0			W	
	V _{OAO}	with respect to SG	-1.3	_	+1.3	V	
	V _{OSVF}	VFRO with respect to SG	-100	_	+100	mV	
Offset Voltage	V	AOUT+, AOUT-, Gain = 1 with	100	_	100	\/	
	V _{OSAO}	respect to SG	-100		+100	mV	

AC Characteristics

					(VDD = +3 (/ ±3%, la =	30 6 10	+03 0)
Parameter	Symbol	Freq. (Hz)	Level (dBm0)	Condition	Min.	Тур.	Max.	Unit
	Loss T1	60			20	26	_	dB
	Loss T2	300			-0.20	+0.07	+0.20	dB
Transmit Fraguency Despense	Loss T3	1020				Reference		dB
Transmit Frequency Response	Loss T4	2020	0		-0.15	-0.04	+0.20	dB
	Loss T5	3000			-0.15	+0.06	+0.20	dB
	Loss T6	3400			0	0.4	0.80	dB
	Loss R1	300			-0.15	-0.03	+0.20	dB
	Loss R2	1020				Reference		dB
Receive Frequency Response	Loss R3	2020	0		-0.15	-0.02	+0.20	dB
	Loss R4	3000			-0.15	+0.15	+0.20	dB
	Loss R5	3400			0.0	0.56	0.80	dB
	SD T1		3		35	43	_	
	SD T2		0		35	41	_	
	SD T3		-30		35	38	_	
Transmit Signal to Distortion Ratio	SD T4	1020	-40	*2 *1 *2	20	31.5		dB
•					29	31.0	_	
	SD T5		–45		0.4	27		
				-43		24	26	_
	SD R1		3		36	43	_	
	SD R2		0		36	41	_	
	SD R3		-30		36	40	_	
Receive Signal to Distortion Ratio	CD D4	1020	40	*2 *1	30	34.5		dB
	SD R4		-4 0			32	_	
	SD R5		-45	*2	0.5	30		
	טח עט		-4 5		25	27		
	GT T1		3		-0.2	+0.01	+0.2	
	GT T2		-10			Reference		
Transmit Gain Tracking	GT T3	1020	-40		-0.2	0	+0.2	dB
	GT T4		-50		-0.4	-0.03	+0.4	
	GT T5		-55		-1.2	+0.15	+1.2	
	GT R1		3		-0.2	-0.06	+0.2	
	GT R2		-10			Reference		
Receive Gain Tracking	GT R3	1020	-40		-0.2	-0.02	+0.2	dB
	GT R4		-50		-0.4	-0.02	+0.4	
	GT R5		-55		-0.8	-0.27	+0.8	

^{*1} Psophometric filter is used

^{*2} Upper is specified for the MSM7543, lower for the MSM7544

AC Characteristics (Continued)

				\	י טטי	±0 /0, 1u =	00 0 10	.00 0,
Parameter	Symbol	Freq.	Level (dBm0)	Condition	Min.	Тур.	Max.	Unit
	N: II T		,	AIN = SG		-74.5	-70	
Idle Channel Noise	Nidle T	_	_	*1 *2	_	-72.5	-69	dBm0p
	Nidle R	_	_	*1 *3	_	-78	-75	
Absolute Level (Initial Difference)	AV T			V _{DD} = 5.0 V	0.580	0.6007	0.622	Virma
Absolute Level (Initial Difference)	AV R			Ta = 25°C *4	0.580	0.6007	0.622	Vrms
Absolute Level (Deviation of Temperature and Power)	AV Tt	1020	0	V _{DD} = +5 V ±5%	-0.2	_	+0.2	dB
	AV Rt			Ta = -30 to 85°C *4	-0.2	_	+0.2	dB
Absolute Delay	Td	1020	0	A to A BCLOCK = 64 kHz	_	_	0.60	ms
	tgd T1	500		*5	_	0.19	0.75	
	tgd T2	600			_	0.11	0.35	
Transmit Group Delay	tgd T3	1000			_	0.02	0.125	ms
	tgd T4	2600			_	0.05	0.125	
	tgd T5	2800			_	0.07	0.75	
	tgd R1	500		*5	_	0.00	0.75	
	tgd R2	600			_	0.00	0.35	
Receive Group Delay	tgd R3	1000	0		_	0.00	0.125	ms
	tgd R4	2600			_	0.09	0.125	
	tgd R5	2800			_	0.12	0.75	
Crosstalk Attenuation	CR T	1020	0	$TRANS \to RECV$	75	80	_	dB
UI USSIAIN AILEITUALIUTI	CR R	1020	U	$RECV \to TRANS$	70	76		ub

^{*1} Psophometric filter is used

^{*2} Upper is specified for the MSM7543, lower for the MSM7544

^{*3} Input "0" code to PCMIN

^{*4} AVR is defined at VFRO output

^{*5} Minimum value of the group delay distortion

AC Characteristics (Continued)

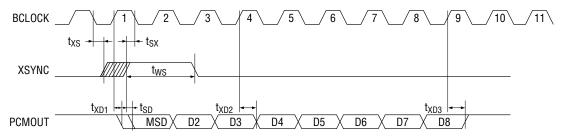
					י סוי טטי	_0 /0, I.u	00 0 10	100 0,
Parameter	Symbol	Freq. (Hz)	Level (dBm0)	Condition	Min.	Тур.	Max.	Unit
Discrimination	DIS	4.6 kHz to 72 kHz	0	0 to 4000 Hz	30	32	_	dB
Out-of-band Spurious	S	300 to 3400	0	4.6 kHz to	_	-37.5	-35	dBm0
Intermodulation Distortion	IMD	fa = 470 fb = 320	-4	2fa – fb	_	-52	-35	dBm0
D-to-D Mode Gain	_	1020	0	TMC = 1 PCMIN to PCMOUT	-1.0	_	+1.0	dB
Power Supply Noise Rejection Ratio	PSR T PSR R	0 to 50 kHz	50 mV _{PP}	*6	_	30	_	dB
	t _{SD}		1		50	_	200	
Digital Output Dalay Time	t _{XD1}	C. 100 .	SE . 1 LOT	TI	50	_	200	
Digital Output Delay Time	t _{XD2}	UL = 100	oF + 1 LST	IL	50		200	ns
	t _{XD3}				50	_	200	

^{*6} The measurement under idle channel noise

TIMING DIAGRAM

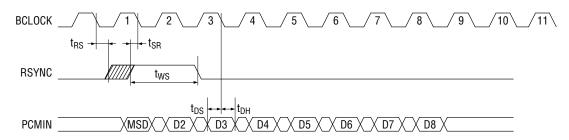
PCM Data Input/Output Timing

Transmit Timing

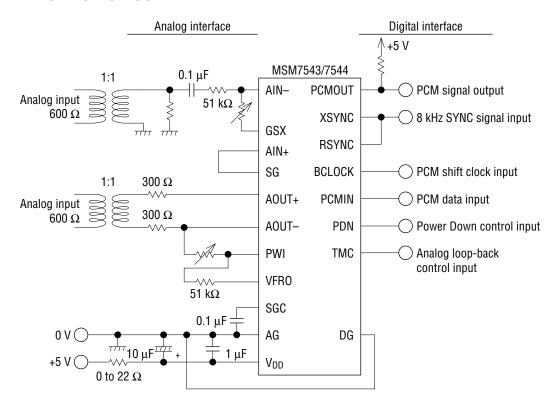


When $t_{XS} \le 1/2 \bullet Fc$, the Delay of the MSD bit is defined as t_{XD1} . When $t_{SX} \le 1/2 \bullet Fc$, the Delay of the MSD bit is defined as t_{SD} .

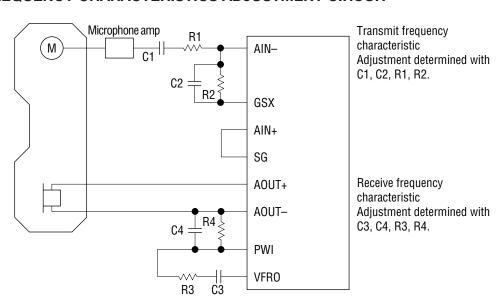
Receive Timing



APPLICATION CIRCUIT



FREQUENCY CHARACTERISTICS ADJUSTMENT CIRCUIT



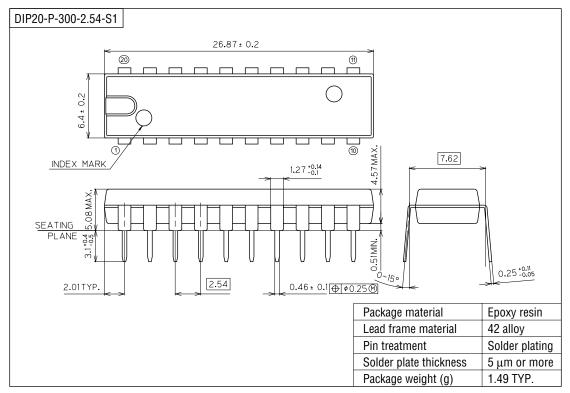
RECOMMENDATIONS FOR ACTUAL DESIGN

• To assure proper electrical characteristics, use bypass capacitors with excellent high frequency characteristics for the power supply and keep them as close as possible to the device pins.

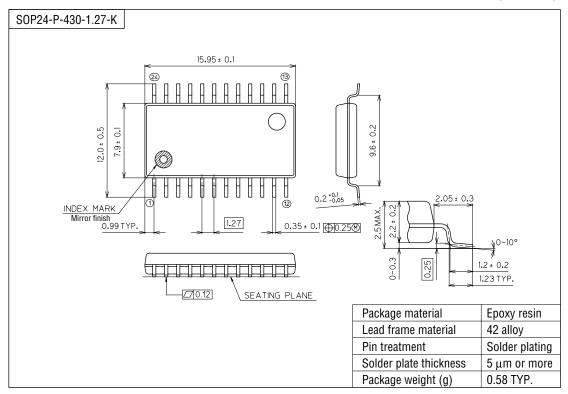
- Connect the AG pin and the DG pin each other as close as possible. Connect to the system ground with low impedance.
- Mount the device directly on the board when mounted on PCBs. Do not use IC sockets. If an IC socket is unavoidable, use the short lead type socket.
- When mounted on a frame, use electro-magnetic shielding, if any electro-magnetic wave source such as power supply transformers surround the device.
- Keep the voltage on the V_{DD} pin not lower than -0.3 V even instantaneously to avoid latchup phenomenon when turning the power on.
- Use a low noise (particularly, low level type of high frequency spike noise or pulse noise) power supply to avoid erroneous operation and the degradation of the characteristics of these devices.

PACKAGE DIMENSIONS

(Unit: mm)



(Unit: mm)

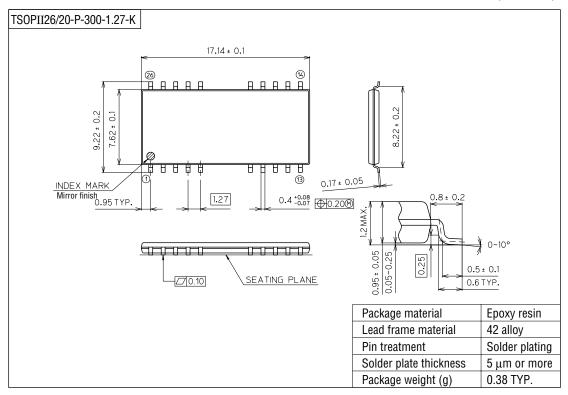


Notes for Mounting the Surface Mount Type Package

The SOP, QFP, TSOP, SOJ, QFJ (PLCC), SHP and BGA are surface mount type packages, which are very susceptible to heat in reflow mounting and humidity absorbed in storage.

Therefore, before you perform reflow mounting, contact Oki's responsible sales person for the product name, package name, pin number, package code and desired mounting conditions (reflow method, temperature and times).

(Unit: mm)



Notes for Mounting the Surface Mount Type Package

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